

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of :
Yoshihisa YAMASHITA et al. : **Attn: APPLICATION BRANCH**
Serial No. NEW : **Docket No. 2001_1854A**
Filed December 27, 2001 :
**LEAD FRAME AND PRODUCTION PROCESS
THEREOF AND PRODUCTION PROCESS OF
THERMALLY CONDUCTIVE SUBSTRATE** **THE COMMISSIONER IS AUTHORIZED
TO CHARGE ANY DEFICIENCY IN THE
FEE FOR THIS PAPER TO DEPOSIT
ACCOUNT NO. 23-0975.**

**COVER LETTER ACCOMPANYING APPLICATION FILED WITHOUT EXECUTED
DECLARATION UNDER 37 CFR 1.53(b) AND IN A LANGUAGE
OTHER THAN ENGLISH UNDER 37 CFR 1.52(d)**

Assistant Commissioner for Patents
Washington, DC 20231

Sir:

Enclosed is a new patent application entitled "LEAD FRAME AND PRODUCTION PROCESS THEREOF AND PRODUCTION PROCESS OF THERMALLY CONDUCTIVE SUBSTRATE". This application is submitted in the Japanese language under the provisions of 37 CFR 1.52(d).

Furthermore, the present application is submitted under the provisions of 37 CFR 1.53(b), and the application as filed does not include an executed declaration. However, accompanying the application is an unexecuted declaration listing the inventor information.

The application as filed further does not include an executed power of attorney, and accordingly, it is requested that communication initially be directed to the following firm, until an executed power of attorney and declaration are filed:

WENDEROTH, LIND & PONACK, L.L.P.
2033 K Street, N.W., Suite 800
Washington, D.C. 20006-1021
Telephone: (202) 721-8200
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The required filing fee of \$740.00 is enclosed.

Respectfully submitted,

Yoshihisa YAMASHITA et al.

By Michael S. Huppert
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Registration No. 40,268
Attorney for Applicants

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December 27, 2001

DECLARATION AND POWER OF ATTORNEY FOR U.S. PATENT APPLICATION

(X) Original () Supplemental () Substitute () PCT () DESIGN

As a below named inventor, I hereby declare that: my residence, post office address and citizenship are as stated below next to my name; that I verily believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural inventors are named below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

Title: LEAD FRAME AND PRODUCTION PROCESS THEREOF AND PRODUCTION PROCESS OF THERMALLY CONDUCTIVE SUBSTRATE

of which is described and claimed in:

() the attached specification, or

(X) the specification in application Serial No. _____, filed December 27, 2001, and with amendments through _____, or

() the specification in International Application No. _____, filed _____, and as amended on _____ (if applicable).

I hereby state that I have reviewed and understand the content of the above-identified specification, including the claims, as amended by any amendment(s) referred to above.

I acknowledge my duty to disclose to the Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, §1.56.

I hereby claim priority benefits under Title 35, United States Code, §119 (and §172 if this application is for a Design) of any application(s) for patent or inventor's certificate listed below and have also identified below any application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

COUNTRY	APPLICATION NO.	DATE OF FILING	PRIORITY CLAIMED
Japan	2000-397650	December 27, 2000	YES
Japan	2000-397651	December 27, 2000	YES

I hereby claim the benefit under Title 35, United States Code §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code §112, I acknowledge the duty to disclose information material to patentability as defined in Title 37, Code of Federal Regulations, §1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

APPLICATION SERIAL NO.	U.S. FILING DATE	STATUS: PATENTED, PENDING, ABANDONED

And I hereby appoint Michael R. Davis, Reg. No. 25,134; Matthew M. Jacob, Reg. No. 25,154; Warren M. Cheek, Jr., Reg. No. 33,367; Nils Pedersen, Reg. No. 33,145; Charles R. Watts, Reg. No. 33,142; and Michael S. Huppert, Reg. No. 40,268, who together constitute the firm of WENDEROTH, LIND & PONACK, L.L.P., as well as any other attorneys and agents associated with Customer No. 000513, to prosecute this application and to transact all business in the U.S. Patent and Trademark Office connected therewith.

I hereby authorize the U.S. attorneys and agents named herein to accept and follow instructions from AOYAMA & PARTNERS as to any action to be taken in the U.S. Patent and Trademark Office regarding this application without direct communication between the U.S. attorneys and myself. In the event of a change in the persons from whom instructions may be taken, the U.S. attorneys named herein will be so notified by me.

Direct Correspondence to Customer No:



000513

PATENT TRADEMARK OFFICE

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Residence & Citizenship	CITY	STATE OR COUNTRY	COUNTRY OF CITIZENSHIP

Post Office Address	ADDRESS	CITY	STATE OR COUNTRY	ZIP CODE
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I further declare that all statements made herein of my own knowledge are true, and that all statements on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

1st Inventor _____ Date _____
Yoshihisa YAMASHITA
2nd Inventor _____ Date _____
Koichi HIRANO
3rd Inventor _____ Date _____
Seiichi NAKATANI
4th Inventor _____ Date _____
Masaki SUZUMURA
5th Inventor _____ Date _____
6th Inventor _____ Date _____

The above application may be more particularly identified as follows:

U.S. Application Serial No. _____ Filing Date December 27, 2001

Applicant Reference Number 534642 Atty Docket No. 2001 1854A

Title of Invention LEAD FRAME AND PRODUCTION PROCESS THEREOF AND PRODUCTION PROCESS OF THERMALLY CONDUCTIVE SUBSTRATE